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2.5 V, 212.00 MHz LVDS Voltage-Controlled Clock Oscillator (VCXO) PureEdge™ Product Series

The NBVSPA013 voltage-controlled crystal oscillator (VCXO) is designed to meet today's requirements for 2.5 V LVDS clock generation applications. These devices use a high Q fundamental mode crystal and Phase Locked Loop (PLL) multiplier to provide 212.00 MHz with a pullable range of ± 100 ppm and a frequency stability of ± 50 ppm. The silicon-based PureEdge $^{\text{\tiny M}}$ products design provides users with exceptional frequency stability and reliability. They produce an ultra low jitter and phase noise LVDS differential output.

The NBVSPA013 is a member of ON Semiconductor's PureEdge clock family that provides accurate and precision clock generation solutions.

Available in the industry standard 5.0 x 7.0 x 1.8 mm SMD (CLCC) package on 16 mm tape and reel in quantities of 1,000 and 100.

Features

- LVDS Differential Output
- Uses High Q Fundamental Mode Crystal
- Ultra Low Jitter and Phase Noise 0.5 ps (12 kHz 20 MHz)
- Pullable Range Minimum of ±100 ppm
- Frequency Stability of ±50 ppm
- Control Voltage with Positive Slope
- Voltage Control Linearity of ±10%
- Hermetically Sealed Ceramic SMD Packages of size 5.0 x 7.0 x 1.8 mm
- Operating Range: 2.5 V ±5%
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Networking
- Networking Base Stations
- Broadcasting



ON Semiconductor®

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6 PIN CLCC LN SUFFIX CASE 848AB



MARKING DIAGRAMS

= Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

1

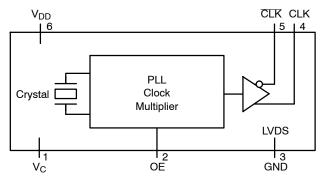


Figure 1. Simplified Logic Diagram

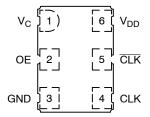


Figure 2. Pin Connections (Top View)

Table 1. PIN DESCRIPTION

| Pin No. | Symbol | I/O | Description |
|---------|-------------------------|-------------------------------|--|
| 1 | V _C (Note 1) | Analog Input | Analog control voltage input pin that adjusts output oscillation frequency. $f_0 = V_C = 1.25 \text{ V}$ |
| 2 | OE | LVTTL/LVCMOS Control Input | Output Enable Pin. When left floating pin defaults to logic HIGH and output is active. See OE pin description Table 2. |
| 3 | GND | Power Supply | Ground at 0 V. Electrical and Case Ground. |
| 4 | CLK | LVDS Output | Non-Inverted Clock Output. Typically loaded with 100 Ω receiver termination resistor across differential pair. |
| 5 | CLK | LVDS Output | Inverted Clock Output. Typically loaded with 100 Ω receiver termination resistor across differential pair. |
| 6 | V_{DD} | Power Supply | Positive Power Supply Voltage. Voltage should not exceed 2.5 V ±5%. |

^{1.} Control voltage has a positive slope with a typical linearity of $\pm 10\%$; $V_C = 1.25 \text{ V} \pm 1 \text{ V}$.

Table 2. OUTPUT ENABLE TRI-STATE FUNCTION

| OE Pin | Output Pins |
|------------|-------------|
| Open | Active |
| HIGH Level | Active |
| LOW Level | High Z |

Table 3. ATTRIBUTES

| Characteristic | | Value | |
|--|-----------------------------------|---------------|--|
| Input Default State Re | sistor | 170 kΩ | |
| ESD Protection | Human Body Model Machine Model | 2 kV 200 V | |
| Meets or Exceeds JEDEC Standard EIA/JESD78 IC Latchup Test | | | |

Table 4. MAXIMUM RATINGS

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Units |
|------------------|---|--------------------------|---|-------------|-------|
| V_{DD} | Positive Power Supply | GND = 0 V | | 4.6 | V |
| V _{IN} | Control Input (V _C and OE) | | $\begin{aligned} V_{IN} &\leq V_{DD} + 200 \text{ mV} \\ V_{IN} &\geq GND - 200 \text{ mV} \end{aligned}$ | | V |
| losc | Output Short Circuit Current CLK to CLK CLK or CLK to GND | Continuous Continuous | | 12 24 | mA |
| T _A | Operating Temperature Range | | | -40 to +85 | °C |
| T _{stg} | Storage Temperature Range | | | -55 to +120 | °C |
| T _{sol} | Wave Solder | See Figure 5 | | 260 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 5. DC CHARACTERISTICS (V_{DD} = 2.5 V $\pm 5\%$, GND = 0 V, T_A = -40° C to $+85^{\circ}$ C) (Note 2)

| Symbol | Characteristic | Conditions | Min. | Тур. | Max. | Units |
|------------------|--|------------|-----------|------|----------|-------|
| I _{DD} | I _{DD} Power Supply Current | | | 75 | 100 | mA |
| V _{IH} | OE and FSEL Input HIGH Voltage | | 2000 | | V_{DD} | mV |
| V _{IL} | OE and FSEL Input LOW Voltage | | GND - 300 | | 800 | mV |
| I _{IH} | Input HIGH Current OE | | -100 | | +100 | μΑ |
| I _{IL} | Input LOW Current OE | | -100 | | +100 | μΑ |
| ΔV_{OD} | Change in Magnitude of V _{OD} for Complementary Output States | (Note 3) | 0 | 1 | 25 | mV |
| V _{OS} | Offset Voltage | | 1125 | | 1375 | mV |
| ΔV _{OS} | Change in Magnitude of V _{OS} for Complementary Output States | (Note 3) | 0 | 1 | 25 | mV |
| V _{OH} | V _{OH} Output HIGH Voltage | | | 1425 | 1600 | mV |
| V _{OL} | V _{OL} Output LOW Voltage | | 900 | 1075 | | mV |
| V _{OD} | Differential Output Voltage | | 250 | | 450 | mV |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 2. Measurement taken with outputs terminated with 100 ohm across differential pair. See Figure 4.
- 3. Parameter guaranteed by design verification not tested in production.

Table 6. AC CHARACTERISTICS (V_{DD} = 2.5 $\pm 5\%$, GND = 0 V, T_A = -40°C to +85°C) (Note 4)

| Symbol | Characteristic | Conditions | Min. | Тур. | Max. | Unit |
|-------------------------|--|--|------|--------|------|------|
| f _{CLKOUT} | Output Clock Frequency | NBVSPA013 | | 212.00 | | MHz |
| Δf | Frequency Stability | (Note 5) | | | ±50 | ppm |
| t _{jit} (φ) | RMS Phase Jitter | 12 kHz to 20 MHz | | 0.4 | 0.9 | ps |
| t _{jitter} | Cycle to Cycle, RMS | 1000 Cycles | | 3 | 8 | ps |
| | Cycle to Cycle, Peak-to-Peak | 1000 Cycles | | 15 | 30 | ps |
| | Period, RMS | 10,000 Cycles | | 2 | 4 | ps |
| | Period, Peak-to-Peak | 10,000 Cycles | | 10 | 20 | ps |
| t _{OE/OD} | Output Enable/Disable Time | | | | 200 | ns |
| F _P | Crystal Pullability (Note 6) | $0 \text{ V} \leq \text{V}_{\text{C}} \leq \text{V}_{\text{DD}}$ | ±100 | | | ppm |
| V _{C(bw)} | Control Voltage Bandwidth | −3 dB | 20 | | | KHz |
| [†] DUTY_CYCLE | Output Clock Duty Cycle (Measured at Cross Point) | | 45 | 50 | 55 | % |
| t _R | Output Rise Time (20% and 80%) | | | 245 | 400 | ps |
| t _F | Output Fall Time (80% and 20%) | | | 245 | 400 | ps |
| t _{start} | Start-up Time | | | 1 | 5 | ms |
| | Aging | 1 st Year | | | 3 | ppm |
| | | Every Year After 1st | | | 1 | |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 4. Measurement taken with outputs terminated with 100 ohm across differential pair. See Figure 4.
- 5. Parameter guarantees 10 years of aging. Includes initial stability at 25°C, shock, vibration and first year aging.
- 6. Gain transfer is positive with a rate of 130 ppm/V.

Table 7. PHASE NOISE PERFORMANCE FOR NBVSPA013

| Parameter | Characteristic | Condition | 212.00 MHZ | Unit |
|-----------|--------------------------------|--------------------|------------|--------|
| ФNOISE | Output Phase-Noise Performance | 100 Hz of Carrier | -82 | dBc/Hz |
| | | 1 kHz of Carrier | -110 | dBc/Hz |
| | | 10 kHz of Carrier | -122 | dBc/Hz |
| | | 100 kHz of Carrier | -123 | dBc/Hz |
| | 1 MHz of C | | -132 | dBc/Hz |
| | | 10 MHz of Carrier | -160 | dBc/Hz |

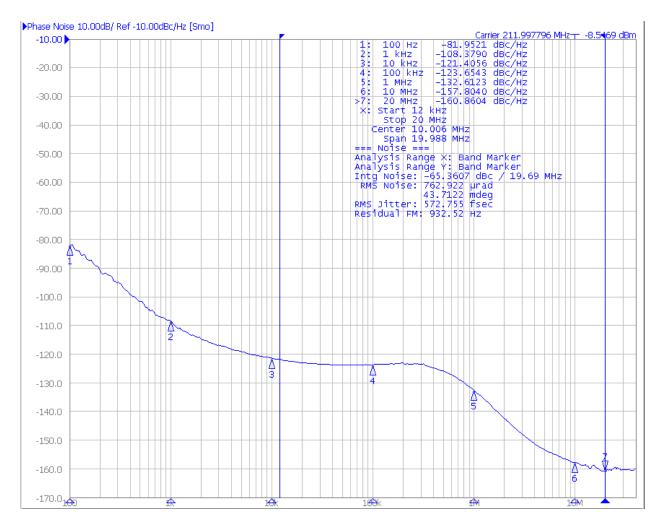


Figure 3. Typical Phase Noise Plot at 212.00 MHz

Table 8. RELIABILITY COMPLIANCE

| Parameter | Standard | Method |
|----------------------------|-------------|---------------------------------------|
| Shock | Mechanical | MIL-STD-833, Method 2002, Condition B |
| Solderability | Mechanical | MIL-STD-833, Method 2003 |
| Vibration | Mechanical | MIL-STD-833, Method 2007, Condition A |
| Solvent Resistance | Mechanical | MIL-STD-202, Method 215 |
| Thermal Shock | Environment | MIL-STD-833, Method 1011, Condition A |
| Moisture Level Sensitivity | Environment | MSL1 260°C per IPC/JEDEC J-STD-020D |

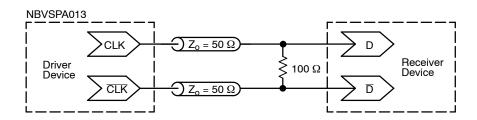


Figure 4. Typical Termination for Output Driver and Device Evaluation

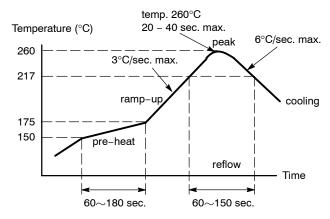


Figure 5. Recommended Reflow Soldering Profile

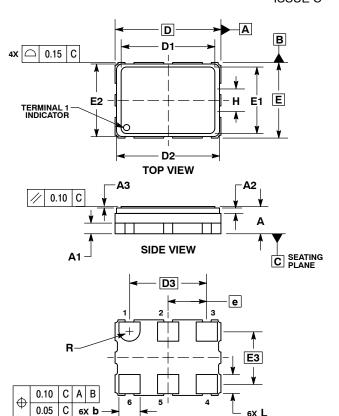
Table 9. ORDERING INFORMATION

| lable of originated in origination | | | | | | | |
|------------------------------------|------------------------|-----------------|-----------------------|--|--|--|--|
| Device | Output Frequency (MHz) | Package | Shipping [†] | | | | |
| 5.0 x 7.0 x 1.8 mm | | | | | | | |
| NBVSPA013LN1TAG | 212.0000 | CLCC-6, Pb-Free | 1000 / Tape & Reel | | | | |
| NBVSPA013LNHTAG | 212.0000 | CLCC-6, Pb-Free | 100 / Tape & Reel | | | | |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and Reel Packaging Specification Brochure, BRD8011/D

PACKAGE DIMENSIONS

6 PIN CLCC, 7x5, 2.54P CASE 848AB ISSUE C



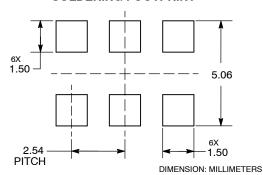
BOTTOM VIEW

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS.

| | MILLIMETERS | | | |
|-----|-------------|----------|------|--|
| DIM | MIN | NOM | MAX | |
| Α | 1.70 | 1.80 | 1.90 | |
| A1 | | | | |
| A2 | | 0.36 REF | | |
| A3 | 0.08 | 0.10 | 0.12 | |
| b | 1.30 | 1.40 | 1.50 | |
| D | | 7.00 BSC | | |
| D1 | 6.17 | 6.20 | 6.23 | |
| D2 | 6.66 | 6.81 | 6.96 | |
| D3 | | 5.08 BSC | | |
| E | | 5.00 BSC | | |
| E1 | 4.37 | 4.40 | 4.43 | |
| E2 | 4.65 | 4.80 | 4.95 | |
| E3 | | 3.49 BSC | | |
| е | 2.54 BSC | | | |
| Н | 1.80 REF | | | |
| L | 1.17 | 1.27 | 1.37 | |
| R | 0.70 REF | | | |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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